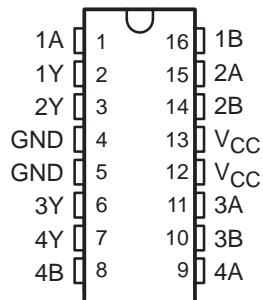


- Inputs Are TTL-Voltage Compatible
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (D), Plastic Thin Shrink Small-Outline (PW), and Standard Plastic 300-mil DIPs (N) Packages

D, N, OR PW PACKAGE
(TOP VIEW)



description

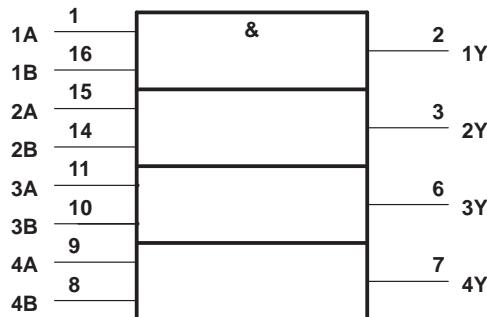
The 74ACT11008 contains four independent 2-input AND gates. It performs the Boolean function $Y = A \cdot B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The 74ACT11008 is characterized for operation from -40°C to 85°C .

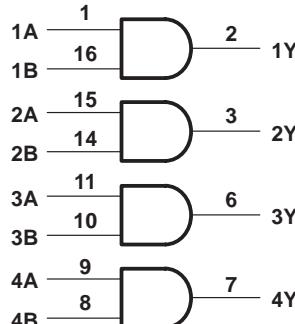
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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74ACT11008 QUADRUPLE 2-INPUT POSITIVE-AND GATE

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{CC}	-0.5 V to 6 V
Input voltage range, V_I (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V_{CC} or GND	± 100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2):	
D package	1.3 W
N package	1.1 W
PW package	0.5 W
Storage temperature range, T_{Stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current		-24	mA
I _{OL}	Low-level output current		24	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T _A	Operating free-air temperature	-40	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT		
			MIN	TYP	MAX					
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4		4.4	4.4	V			
		5.5 V	5.4		5.4					
	I _{OH} = -24 mA	4.5 V	3.94		3.7	3.7				
		5.5 V	4.94		4.7					
V _{OL}	I _{OL} = 50 µA	4.5 V		0.1	0.1	0.1	V			
		5.5 V		0.1	0.1					
	I _{OL} = 24 mA	4.5 V		0.36	0.44	0.44				
		5.5 V		0.36	0.44					
I _{OH} [†]	V _O = 3.85 V	5.5 V				-75		mA		
I _{OL} [†]	V _O = 1.65 V	5.5 V				75		mA		
I _I	V _I = V _{CC} or GND	5.5 V		±0.1		±1		µA		
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		4		40		µA		
ΔI _{CC} [‡]	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.9		1		mA		
C _i	V _I = V _{CC} or GND	5 V		3.5				pF		

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 1 second.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 or V_{CC}.

switching characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	Y	1.5	5.8	8	1.5	9	ns
			1.5	5.2	7.7			

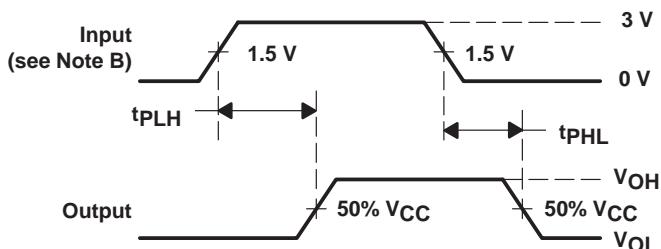
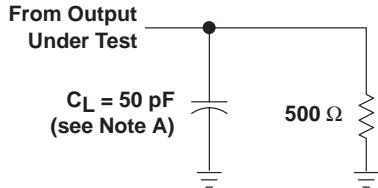
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per gate	C _L = 50 pF, f = 1 MHz	29	pF

74ACT11008 QUADRUPLE 2-INPUT POSITIVE-AND GATE

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PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
74ACT11008D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
74ACT11008DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
74ACT11008NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
74ACT11008PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74ACT11008PWLE	OBsolete	TSSOP	PW	16		TBD	Call TI	Call TI	Samples Not Available
74ACT11008PWR	ACTIVE	TSSOP	PW	16		TBD	Call TI	Call TI	Purchase Samples
74ACT11008PWRE4	ACTIVE	TSSOP	PW	16		TBD	Call TI	Call TI	Purchase Samples
74ACT11008PWRG4	ACTIVE	TSSOP	PW	16		TBD	Call TI	Call TI	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

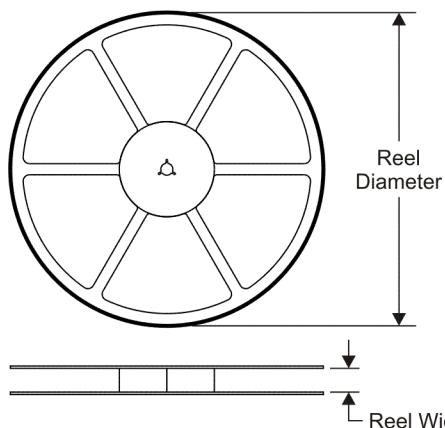
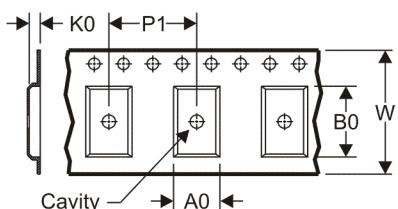
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

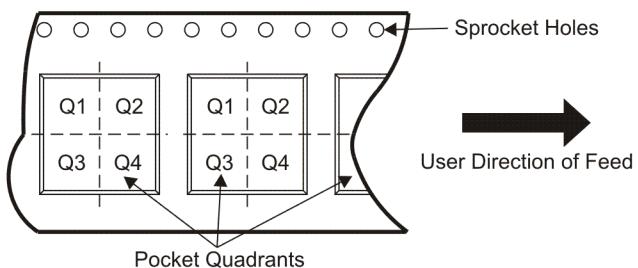
(³) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11008DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

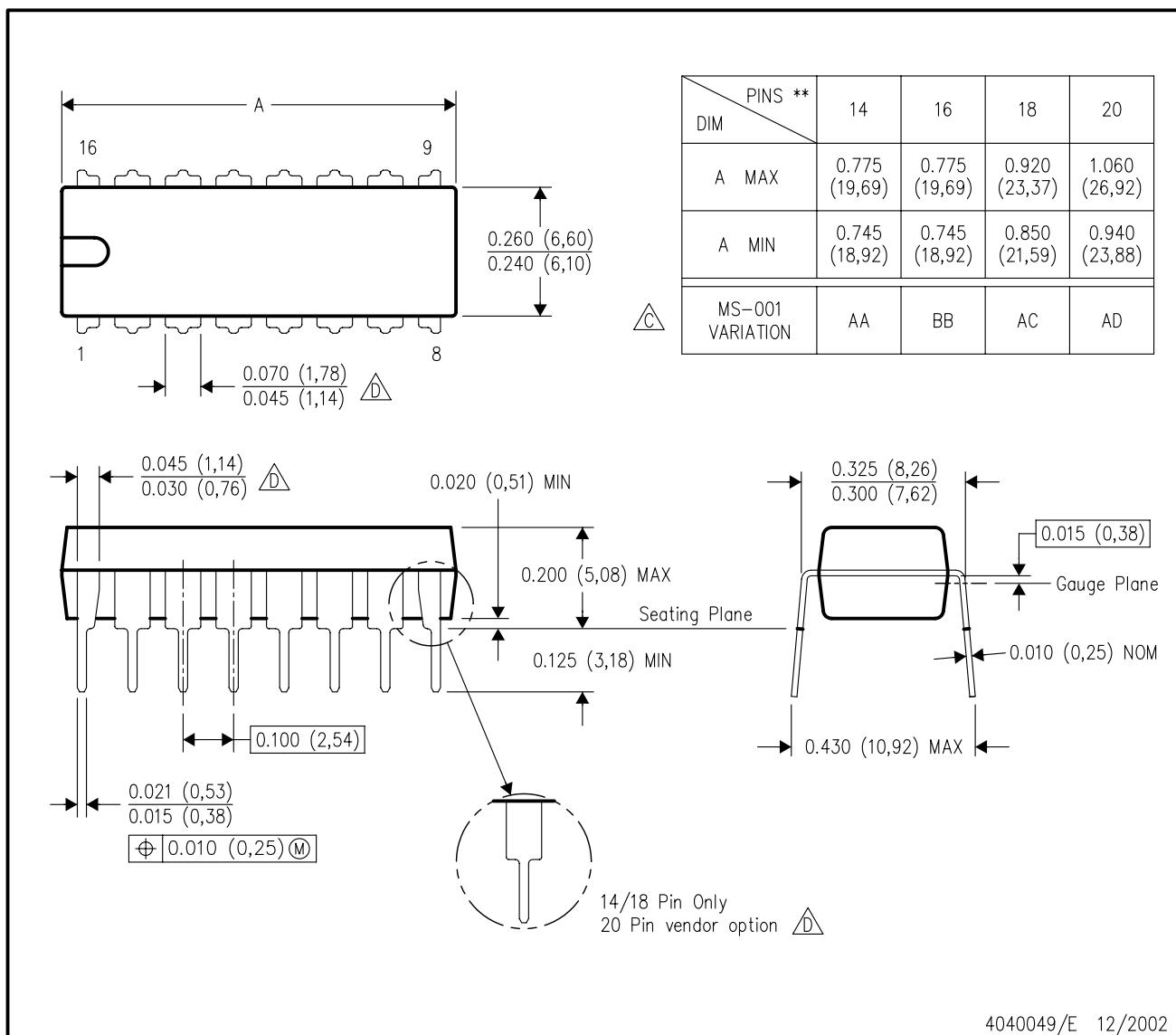
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT11008DR	SOIC	D	16	2500	333.2	345.9	28.6

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



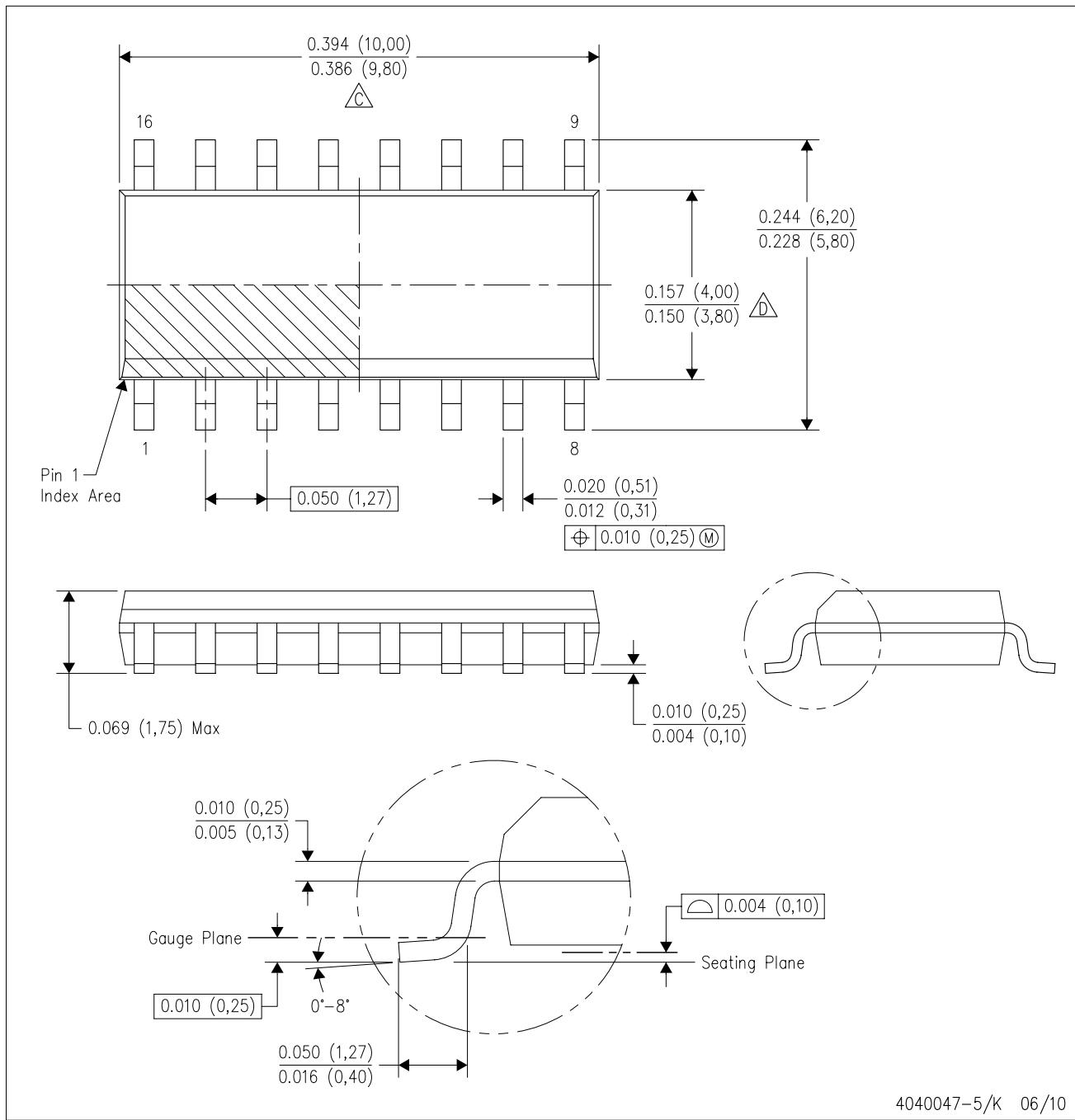
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

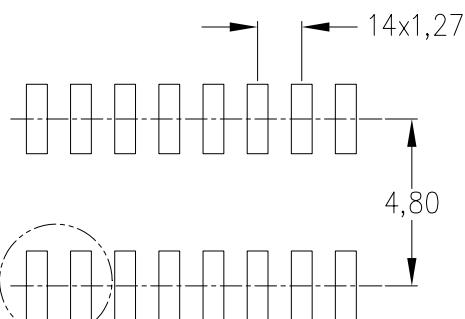
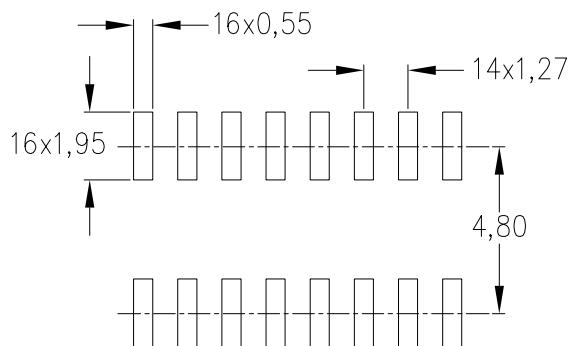
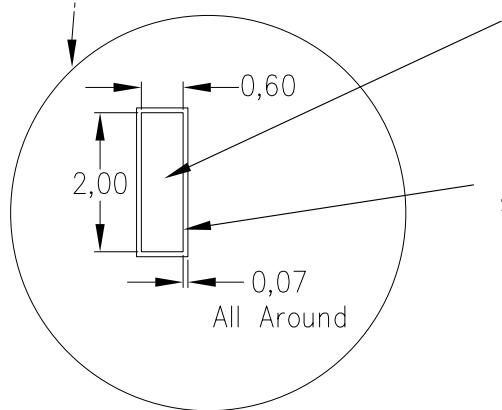
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)Example
Non Soldermask Defined PadExample
Pad Geometry
(See Note C)Example
Solder Mask Opening
(See Note E)

4211283-4/A 08/10

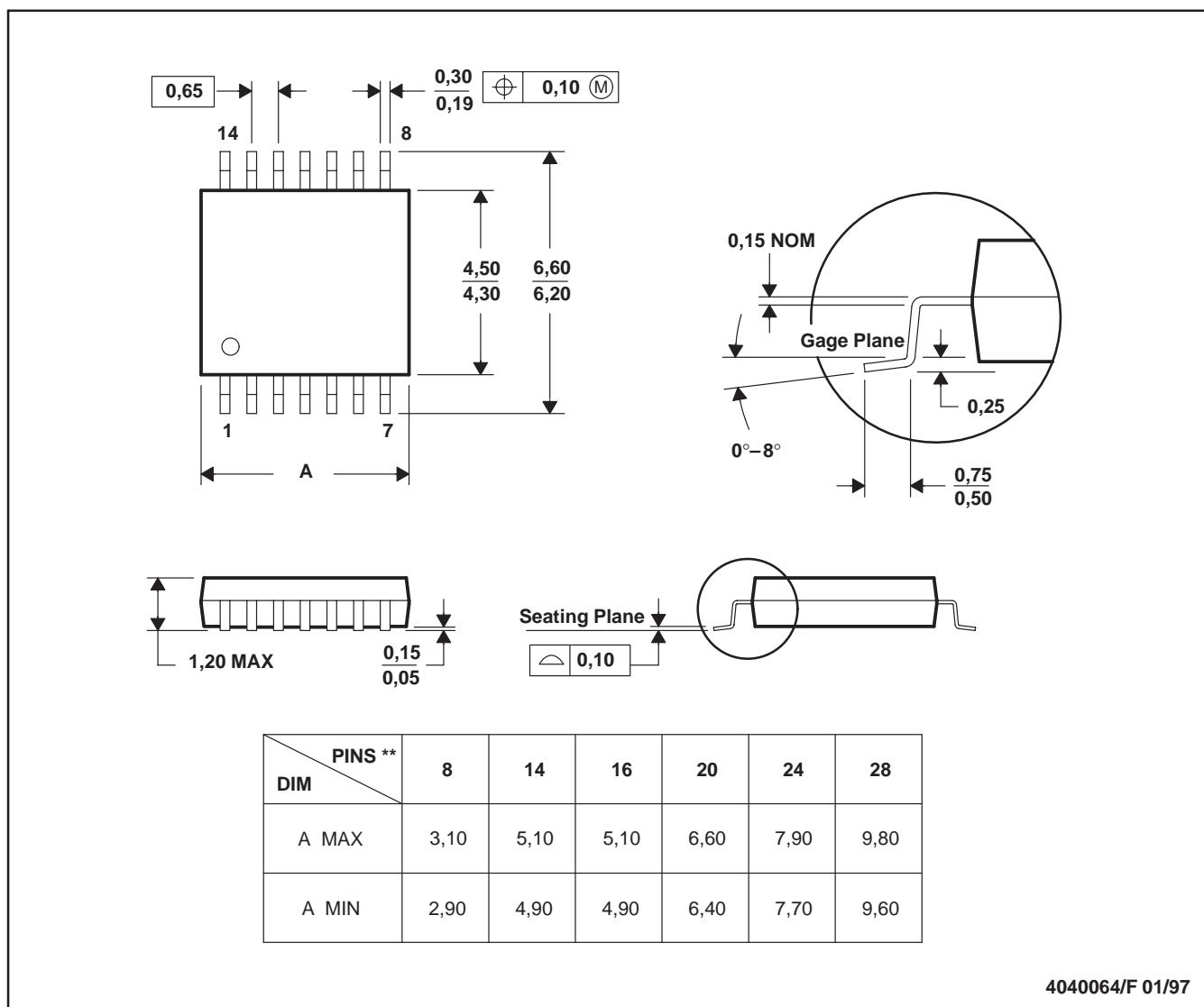
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

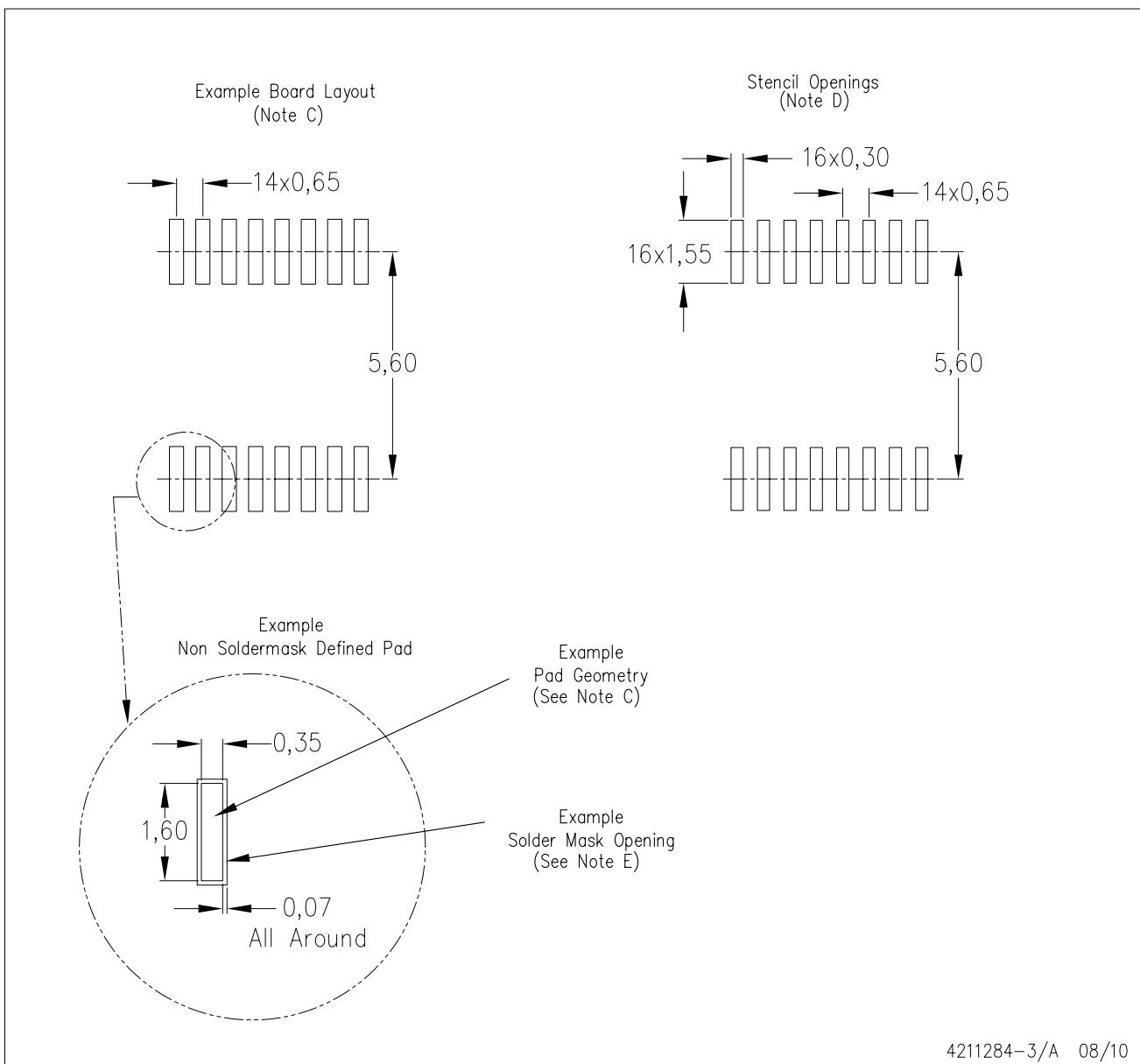


NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/A 08/10

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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